

**WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY MODULE
AND METHODS FOR MAKING AND IMPLEMENTING THE SAME**

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ABSTRACT OF THE DISCLOSURE

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An apparatus for preparing a wafer is provided. The apparatus includes a wafer backside plate and a central shaft. The wafer backside plate has a top surface that includes a cylindrical edge lip, which defines a central aperture. The central shaft is designed to fit within the central aperture. The wafer backside plate is designed to automatically slide between an up position during rotational wafer processing and a down position when the wafer is not in rotational wafer processing. A gap defined between the top surface of the wafer backside plate and the wafer is less when the wafer backside plate is in the up position than when the wafer backside plate is in the down position.

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